

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/19/11871	
1.3 Title of PCN	STM32G4 improvement	
1.4 Product Category	change 1: all STM32G4 products change 2: LeadFrame change only for STM32G4 products in LQFP64 and LQFP100 packages	
1.5 Issue date	2019-12-19	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	FRANCKE CHRISTIANE
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2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	change 1 : TSMC FAB14 (Taiwan) change 2 : StatsChippac-SCCJ (China), Amkor ATP (The Philippines)

4. Description of change

	Old	New
4.1 Description	(change 1) Limitations described in ErrataSheets : - ES0430 Rev1 April 2019 for STM32G471xx/473xx/474xx/483xx/484xx devices. - ES0431 Rev1 April 2019 for STM32G431xx/441xx devices. (change 2) Mount and Bonding Diagram (MBD) Bill of material (BOM) change for LQFP64 and LQFP100 package	(change 1) Limitations removed from ErrataSheets : - ES0430 Rev2 for STM32G471xx/473xx/474xx/483xx/484xx devices. - ES0431 Rev2 for STM32G431xx/441xx devices. (change 2) Mount and Bonding Diagram: New MBD Bill Of Material: New Leadframe for LQFP64 and LQFP100 packages
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No Change	

5. Reason / motivation for change

5.1 Motivation	QUALITY IMPROVEMENT - Correction of some limitations
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	see PCN11871 additional documentation
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7. Timing / schedule

7.1 Date of qualification results	2020-01-24
7.2 Intended start of delivery	2020-01-24
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
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8.1 Description	11871 Binder -MDG-MCD_RER1904 V1.1 - STM32G431x _ RER1703 V2.1-STM32G47x - STM32G48x.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-12-19

9. Attachments (additional documentations)			
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11871 Public product.pdf
 11871 Binder -MDG-MCD_RER1904 V1.1 - STM32G431x _ RER1703 V2.1-STM32G47x -STM32G48x.pdf
 11871 PCN11871_Additional information.pdf

10. Affected parts		
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
3132402	STM32G431CBT6	
3132403	STM32G431CBU3	
3132404	STM32G431CBU6	
3132405	STM32G431KBT6	
3132406	STM32G431KBU3	
3132408	STM32G431KBU6	
3132387	STM32G431RBI6	
3132409	STM32G431RBT6	
3132410	STM32G431VBT6	
3132411	STM32G441CBT6	
3132412	STM32G441CBU6	
3132413	STM32G441KBT6	
3132414	STM32G441KBU6	
3132415	STM32G441RBT6	
3132416	STM32G441VBT6	
3132388	STM32G473CET6	
	STM32G473CEU6	
3132417	STM32G473VET6	
3132391	STM32G474CET6	
3132392	STM32G474CEU6	
3132393	STM32G474QET3	
3132394	STM32G474RBT3	
3132418	STM32G474RET6	
3132395	STM32G474VEH6	
3132421	STM32G474VET6	
3132396	STM32G483CET6	
	STM32G483RET6	
	STM32G483VET6	
	STM32G484CET6	
	STM32G484CEU6	
3132397	STM32G484QET6	
3132422	STM32G484RET6	
	STM32G484VET6	

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